Low melting temperature compliant solders are disclosed. In one particular exemplary embodiment, a low melting temperature compliant solder alloy comprises from about 91.5% to about 97.998% by weight tin, from about 0.001% to about 3.5% by weight silver, from about 0.0% to about 1.0% by weight copper, and from about 2.001% to about 4.0% by weight indium.
A. CLASSIFICATION OF SUBJECT MATTER

IPCP(8) - B23K35/24 (2006.01); C22C 13/00 (2006.01)

USPC - 420/S87, 420/S80, 148/24, 75/255

According to International Patent Classification (IPC) or IPC/both in the cited documents: C22C25/35/24 and B23K

B. CLASSIFICATION

Minimum document citation noted as follows (of the full citation system reproduced by the full citation system itself)

IPC(8) - B23K35/24

USPC - 420/S87, 420/S80, 148/24, 75/255

C. D O C U M N E T S CONSIDERED TO BE RELAVANT

Citation of document, Will indication, where appropriate, of the relevant passage.

Relevance claim No.

<table>
<thead>
<tr>
<th>No.</th>
<th>Citation of document, Will indication, where appropriate, of the relevant passage.</th>
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</tr>
</thead>
<tbody>
<tr>
<td>X</td>
<td>US 6,428,911 B2 (Klitajima et al) 6 August 2002 (06/08/2002), abstract</td>
<td>1-6</td>
</tr>
<tr>
<td>Y</td>
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</tr>
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<td>US 6,559,262 B1 (Shoiji) 27 May 2003 (27/06/2003), col 3, in 17-30, col 5, in 33-36</td>
<td>7-14</td>
</tr>
</tbody>
</table>

Further documents are listed in the coapplicant's D/P or C/C.

T = to the international filing date. D = alone or in combination with the applicant's filing date. I = alone or in combination with the international filing date. U = alone or in combination with the national filing date. R = along with relevant passage. 

Date of the actual completion of the international检索

12 February 2007 (12-1-2007)

Application Lang English of the ISA/US

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Facsimile No. 751-273-3201